PCB Fabrication Notes Unless otherwise specified, all dimensions are in inches Overall Dimension: 3.305" x 2.57" Finished Thickness: .062" **Layer Count: 2 Drill Count: 177** PAD Count: 706 Solder Mask: Green LPI SMOBC **Legend: White Non-Conductive Ink LPI Process** RS274-X Gerber Format, 2.5 Leading Zeros Suppressed **Excellon Drill Format, 2.5 Trailing Zeros Suppressed Layer Details POLARITY** .GTL **Top Copper POSITIVE** .GBL **Bottom Copper POSITIVE N-Layer Stackup** .GTO **Top Silkscreen Bottom Silkscreen** .GBO .GTS **Top Soldermask Bottom Soldermask** .GBS .TXT **NC-DRILL** FPGA Mark 1 M. Jones

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Rev: α





